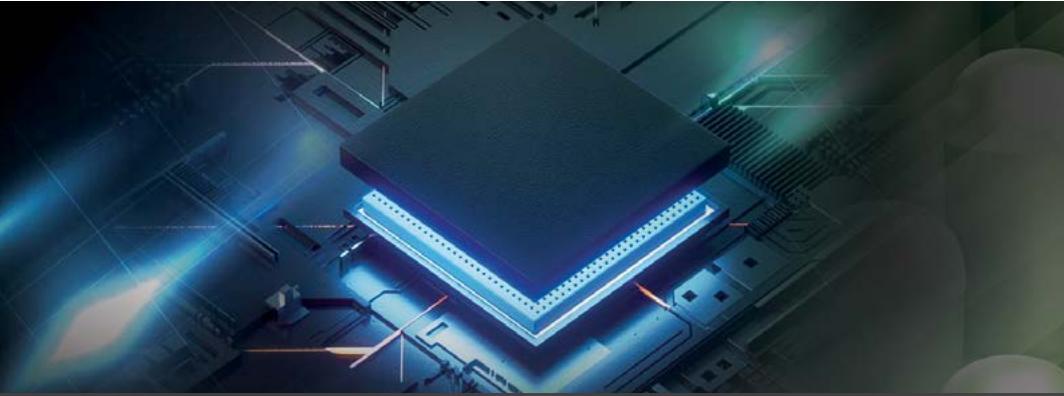# Best in Class, Multi-Sensor Metrology

ΜICROPROF®AP

MicroProf® AP is the most versatile metrology tool on the market. Its multi-sensor setup and software packages provide metrology data throughout Advanced Packaging processes.

- PI and PR film thickness and opening
- CD and overlay
- TSV metrology, fill monitoring, trenches
- Flatness and uniformity after CMP
- Copper erosion and dishing (Hybrid Bonding)
- UBM height and roughness
- RDL thickness, width and roughness
- Bump and nail height, diameter and coplanarity
- Bow and stress
- Carrier, adhesive, bonded wafer thickness and TTV

3D Metrology

Metrology Capabilities	• Customizable for any semiconductor metrology requirements by multi-sensor setup • Addresses all metrology requirements that come with advanced packaging technology
Wafer Handling Capabilities	• Fast, safe and precise wafer handling • Wafer handling and chucks are customizable to any kind of wafer type and size (300, 200 or 150 mm) • Three-point or vacuum wafer positioning • Optimized for high throughput with dual loadports, Pre-aligner and RFID Reader • Optional add-ons for open-cassette handling (150 or 200 mm wafers), Bridge tool option (two wafer sizes in one tool), Edge grip handling option etc. • Film frame wafer handling available
EFEM Enclosure	• ISO class 3 clean room conformal housing • 2 filter fan units (FFU), one for handling and one for metrology area
Metrology Software Acquire Automation XT	• Highly customizable software for fully automated semiconductor metrology • Optimized for precision as well as throughput • Tailored control for each sensor type • Tailored evaluation for any measurement task required • Trans-machine controls and settings via recipes